

Docket No.: 2336-247

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:
	:
Joo Ho LEE <i>et al.</i>	: <i>Confirmation No. 2626</i>
	:
U.S. Patent Application No. 10/790,723	: Group Art Unit: 2826
	:
Filed: March 3, 2004	: Examiner: Fetsum Abraham
For: WAFER LEVEL PACKAGE FOR MICRO DEVICE AND MANUFACTURING METHOD THEREOF	

AMENDMENT

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria VA 22313-1450

Sir:

The following amendments and remarks are submitted in response to the Official Action dated *March 27, 2006*.